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(54) **PCB LAND PAD FOR THREE-PIN MOSFET COMPONENT**

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(57)

ABSTRACT

A printed circuit board (PCB) land pad for a three-pin metal-oxide-semiconductor field-effect transistor (MOSFET) component comprises four pads with a split pad for a drain terminal of the MOSFET component. The PCB land pad comprises: a first pad to connect a gate terminal of the MOSFET component to a PCB; a second pad to connect a source terminal of the MOSFET component to the PCB; a third pad corresponding to connect a drain terminal of the MOSFET component to the PCB; and a fourth pad to connect the drain terminal of the MOSFET component to the PCB.

